

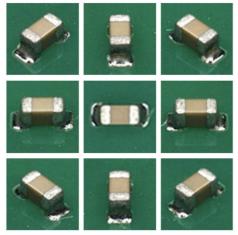
# In-Line 3D Automatic Optical Inspection System

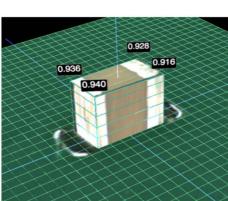
7	Revolutionary 3D imaging technology	True 3D imaging, Side cameras integrated in 3D processing.
<b>V</b>	High Speed 90Fps USB 3 Vision Cameras	The latest generation of high speed, high quality cameras No capture card requirements.
	2X FOV over previous Generation	Up to 50% reduction of cycle time.
<b>V</b>	Multi-color 4 angle lighting with Line Source Coaxial Lighting and Meniscus Profiler	reliable solder joint meniscus and pad surface analysis (to find meniscus and paste printing defects)
$\sqrt{}$	Inspects:	use inspection in all stages of the production process
1	Flexible classification and reporting scenarios	integrate AOI efficiently in your existing operations and factory lay-out
	Line Sourced DOAL(Direct On Axis Lighting) coaxial lighting system with high resolution Telecentric Optics	inspect solder joints without shadow effects from tall components nearby and accurate inspection model building
	Low Noise Large CCD High Speed 24 bit Color Camera	find defects easier including printing defects on Gold or Cu plated PCB's
	Synthetic Imaging and Spectral Analysis	powerful algorithms to achieve an optimal balance between defect detection and false reject levels in shortest time
	Triple use of side camera's	Use for automatic inspection, classification and repair
	Prototype mode for 1st off inspection	program in minutes to verify your production line is set-up correctly before starting full production
	In height adjustable optical head	Compensate for PCB warp and adapt to tall component and sandwich assemblies



# Enwertpector GTz/GTAz/GDAz

## **Hardware and Software Features**





## **Revolutionary 3D imaging**

True Stereoscopic imaging using 9 cameras. Full colour 3D allows the ability to actually see the side of components rather than extruded 2D images. Using the addition of a 4th LED white light





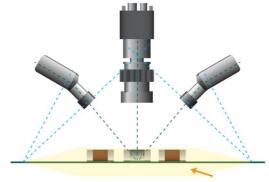


## The perfect combination of 3D and 2D inspection

Height, tilt and coplanarity measurement. Pin Height measurement Component Presence Absence, Polarity, Value, Angle, Offset, Colour, Extra part detection, Solder ball detection, Solder profile analysis and short detection. The thickness of chip capacitors in combination with colour makes a more reliable inspection when checking chip capacitors value.

#### **Unique 3D Stereoscopic Vision**

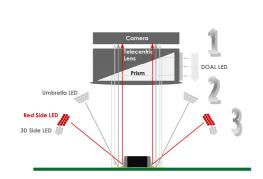
Utilizing the full 9 cameras of the MEK camera head. The image differential are merged and a vectorised map of the component is created. Then analyzed based on the programmers applied tolerances. The vectorised map of the components removes the minor imperfection of the component surface giving more accurate measurement of height and surface angle of the component with reduced chance of false readings.



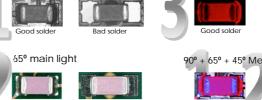
45° side light

### Omnidirectional multi angle, multi color LED lighting

Optimal light no matter component direction — 3D color profile of solder meniscus — Reliable defect decision by the software — Decide Good Solder, No Solder, Lack of Solder and Too much solder for SMT and THT solder joints









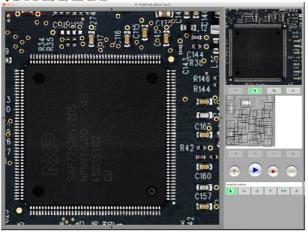
### 8x Angular Side Sensors (Only available for FDA and FDAz models)

Simultaneously operating, multiplexed side view sensors with CameraLink interface — 45/45 arrangement — Triple use: Active automatic inspection, classification and repair — clear 9 angles defect review — high magnification 50x (10µm/pixel) — Full Color — Auto highlight — Large sensor pixels — 9 view images also in backup database



# Enwertpectur GTz/GTAz/GDAz

## Hardware and Software Features — Continued

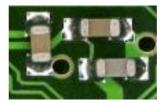


### Double size FOV (Field of view)

Up to 2x faster inspection over previous generations of machines. Square FOV combined with circular lighting allows for program rotation without time consuming debugging.

### Large pixel image capturing sensor

 $18.8 \mu m^2$  pixel size — less noise — smooth and detailed image— great dynamic range



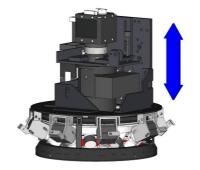


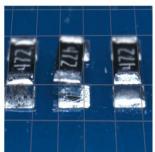
High dynamics sensor

Conventional sensor

### In Height Adjustable Optical Head

In Z-Axis moving Top Camera, Light and Side View cameras — Adaption to any PCB Thickness — PCB Warp Compensation — Inspection of PCB's with very tall components — Reliable text and/or polarity inspection on tall components Inspection of "Sandwich" assemblies without need of jigs and multiple inspections



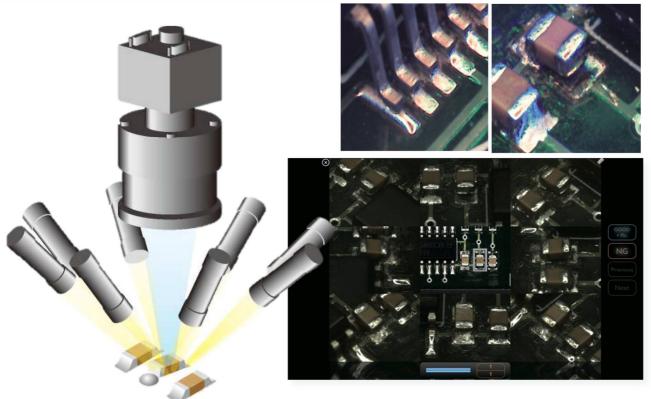




Shift & Tilt Side View lenses

Distortion free side images across whole FoV. Every point on the PCB within the FoV has same distance to the capturing sensor despite the angle of the optics

Without Shift&Tilt Shift&Tilt





# **Inline**

# Enwertpector

# **GTAZ/GDAZ** 350L, 650L, 800L

In-Line Series Specifications	PowerSpector GTAz 350L	PowerSpector GTAz 650L	PowerSpector GTAz 800L			
Maximum PCB Size	350x250mm (13.8"x9.8")	650x550mm (25.6"x21.6")	800x550mm (31.5"x21.6")			
	Note: GDAz Max. PCB Size	is slightly smaller due to lar	ger diameter optical unit			
Characteristics						
Product type	Automatic Optical Inspector					
In-line/Off-line		In-Line				
Camera movement	X + Y Direction					
PCB movement	Stationary during inspection					
Parts inspection	Presence, Polarity, Offset, Correctness, Soldering, Height					
Printing/paste inspection	Offset, Smearing, Bridges, Uniformity					
Image Processing	Synthetic Imaging, Spectral Analysis, Greyscale limits					
Image Parameters	Brightness, Hue, Saturation via Filters					
Camera type	Digital color Thunderbolt interface 90 Fps					
Camera Field Of View/Resolution	38.5x38.5mm(1.52″x1.52″)/18.75μm or 19.5x19.5mm(0.77″x0.77″)/10μm					
Lens	Telecentric lens with built in prism for DOAL Lighting					
	Omnidirectional T Quad	Omnidirectional T Quad LED rings: Side White, Side Red, Main, Line Sourced				
Lighting system		Diffused On Axis Lighting (C				
Specifications						
Minimum inspection component size	01005" (0.4x0.2mm) (10μm resolution)					
Positioning accuracy	Pixel related Feedback Loop					
Component clearance (top)	GTAZ	GTAz 30mm (1.2")/ GDAz 60mm (2.4")				
Side Cameras	8x Digital color USB 3.0 Vision in 45/45 orientation					
Z-Axis movement range	30mm (1.2")					
Component clearance (bottom)	35mm (1.38") or 55mm (2.17") without PCB support lift option					
Movement speed	720mm/s					
Inspection capacity typical	2750ppm					
Electrical requirements	100-240 VAC / 330W					
Conveyor						
Conveyor belt speed	10-500mm/s (0.4-19.7"/s)					
Conveyor configuration	Left>Right, Front rail fixed, Height 830-950mm					
PCB Clamping	Top Justified, Ruler Blade, Top & Edge Clamping, Sensor Stopper					
Minimum board size	50x50mm (2.0" x 2.0")					
Board thickness	0.6-2mm (option 0.6-4mm) (24mils - 79mils)					
PCB warpage compensation	Automatic PCB support Lift with magnetic pins (option)					
Interfacing						
Control PC type	Apple Mac Mini or iMac					
Control interface		SMEMA (conveyer)				
Data interface	USB and Thunderbolt					
Programming Interface	CSV Centroid file (Placement file)					
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windows 7/8/10) (option)					
3rd party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)					
Genera						
Operating temperature	15-30 deg. C(60-90 deg. F)					
Operating humidity		15-80 % RH				
	W740 x D786 x H1236	W1040 x D1077 x H1270	W1190 x D1077 x H1259			
External size	(29.1" x 30.9" x 48.7")	(40.9" x 42.4" x 50.0")	(46.9" x 42.4" x 49.5")			
Weight	180kg (397lbs)	240kg (529lbs)	290kg (639lbs)			

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# **Inline**

# Pawerspectar

**GTZ** 350L, 650L, 800L

In-Line Series Specifications	PowerSpector GTz 350L	PowerSpector GTz 650L	PowerSpector GTz 800L		
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Product type	Automatic Optical Inspector				
In-line/Off-line	In-Line				
Camera movement	X + Y Direction				
PCB movement	Stationary during inspection				
Parts inspection	Presence, Polarity, Offset, Correctness, Soldering, Height				
Printing/paste inspection	Offs	Offset, Smearing, Bridges, Uniformity			
Image Processing	Synthetic Ima	Synthetic Imaging, Spectral Analysis, Greyscale limits			
Image Parameters	Brigi	Brightness, Hue, Saturation via Filters			
Camera type	Digital color Thunderbolt interface 90 Fps				
Camera Field Of View/Resolution	38.5x38.5mm(1.52"x1.52")/18.75μm or 19.5x19.5mm(0.77"x0.77")/10μm				
Lens	Telecentric	Telecentric lens with built in prism for DOAL Lighting			
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Lighting system	Omnidirectional T Quad LED rings: Side White, Side Red, Main, Line Sourced DOAL (Diffused On Axis Lighting (Coaxial))				
Specifications					
Minimum inspection component size	01005" (0.4x0.2mm)(10µm resolution)				
Positioning accuracy	Pixel related Feedback Loop				
Component clearance (top)	50mm (2.0")				
Side Cameras	No Side Cameras				
Z-Axis movement range	30mm (1.2")				
Component clearance (bottom)	35mm (1.38") or 55mm (2.17") without PCB support lift option				
Movement speed	720mm/s				
Inspection capacity typical	2750ppm				
Electrical requirements	100-240 VAC / 330W				
Conveyor					
Conveyor belt speed	10-500mm/s (0.4-19.7"/s)				
Conveyor configuration	Left>Right, Front rail fixed, Height 830-950mm				
PCB Clamping	Top Justified, Ruler Blade, Top & Edge Clamping, Sensor Stopper				
Minimum board size	50x50mm (2.0" x 2.0")				
Board thickness	0.6-2mm (option 0.6-4mm) (24mils - 79mils)				
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Control PC type	Apple Mac Mini or iMac				
Control interface	SMEMA (conveyer)				
Data interface	USB and Thunderbolt				
Programming Interface	CSV Centroid file (Placement file)				
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windows 7/8/10) (option)				
3rd party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)				
General					
Operating temperature	15-30 deg. C(60-90 deg. F)				
Operating humidity	15-80 % RH				
	W740 x D786 x H1236	W1040 x D1077 x H1270	W1190 x D1077 x H1259		
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